 Chip on board / Wire Bonding Design Guide

**Design Rules for Aluminium (Al) wire bonding**

- Chip Pad x/y: > 80 µm
- Chip to substrate pad 1.5 x chip thickness
- Substrate pad length 300 µm
- Al wires can be bonded at any angle between chip pad to substrate pad.

**Chip pad to substrate pad orientation is parallel.**

**Design Rules for Gold (Au) wire bonding**

- Chip Pad x/y: > 80 µm
- Chip to substrate pad 1.5 x chip thickness
- Substrate pad length 300 µm
- Substrate pad width ≥ 150 µm
- Space ≥ 100 µm

**Chip pad to substrate pad must be aligned in the same direction.**

- The solder mask must be released as block in the area of the bond pads.